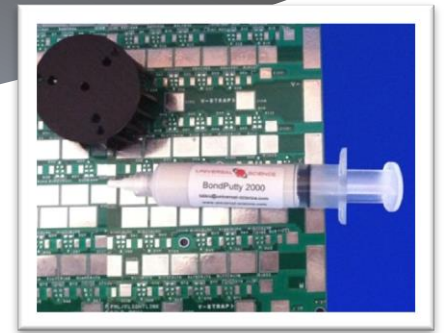


BondPutty 2000

Thermal Bonding Adhesive



BondPutty 2000 is a silicone, liquid adhesive that cures to form a strong bonding thermally conductive and dielectric elastomeric bond.

Pre-cure **BondPutty 2000** is viscous and paste-like in consistency enabling manual or automatic dispensing into a wide variety of applications. Cure occurs at elevated temperatures of above 100°C. **BondPutty 2000** is a neutral and non-corrosive compound, recommended for the encapsulation of electronic assembly devices. The cured structural bond of **BondPutty 2000** will maintain optimum thermal performance and bond strength between temperatures of -50°C to 200°C.

Features

- One part dispensing, silicone based, adhesive paste compound- before cure
- Thermal conductivity = 2.0 W/mK
- Post-cure forms a strong, structural, adhesive bond
- Completely neutral and non-corrosive to components and metalwork

Availability and Storage

- Typically supplied in cartridges or bulk pail containers, other types of packaging are considered on request
- Shelf life of 12 months at temperatures $\leq 5^\circ\text{C}$

Physical Properties

(Post-cure: 1 hour at 125°C, 3mm thick)

Property (unit)	Test Method	BondPutty 2000
Colour	Visual	Grey
Operating Temp.(°C)	In House	-45 to +210
Thermal Conductivity (W/mK)	ASTM D5470	2.0
Hardness (Shore A)	ASTM D2240-95	50
Specific Gravity	ASTMD70	2.15
Viscosity – pre-cure (mPas)	Brookfield	140,000

Benefits and Applications

- Cures to form a strong elastomeric bond that delivers excellent thermally conductive and dielectric properties
- Non-corrosive, tough yet flexible bond
- Suitable for use in chemically sensitive applications and encapsulating electronic assembly devices

Application and Cure

- Cure rate dependent on time taken for sealant to reach required curing temperature and amount dispensed
- Small beads of 1mm to 2mm can be cured with air gun
- Thicker beads or sections require the use of an air circulating oven or induction heating source

Electrical and Mechanical Properties: (Post-cure: 1 hour at 125°C, 3mm thick)

Property (unit)	Test Method	BondPutty 2000
Dielectric Strength (V/mm)	ASTM D149	>18,000
Volume Resistivity ($\Omega\text{-cm}$)	ASTM D257	3.4×10^{13}
Tensile Strength (MPa)	ASTM 412	2.10
Elongation at Break (%)	ASTM 412	103
Coefficient of Thermal Expansion Volumetric – Linear (ppm/°C)	-	580 – 190



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This material is often used in these industries:



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LED



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PSU

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